

Amendments to the Claims:

Please cancel claims 1 – 11.

12. (New) A mobile phone structure that can attenuate undesirable electro-magnetic waves prevalent at abrupt discontinuities of metallized areas within the mobile phone during normal operation of the mobile phone, the mobile phone structure comprising:

an impedance layer comprised of a non-ferrous metallic layer substantially covering the metallized areas wherein the non-ferrous metallic layer reduces the effect of undesirable electro-magnetic waves on the side of the non-ferrous metallic layer opposite the substantially covered metallized areas.

13. (New) The mobile phone structure of claim 12 wherein the impedance layer further comprises a dielectric substrate layer having inner and outer surfaces coupled with the non-ferrous metallic layer.

14. (New) The mobile phone structure of claim 13 wherein the non-ferrous metallic layer is coupled to the inner surface of the dielectric substrate layer.

15. (New) The mobile phone structure of claim 13 wherein the non-ferrous metallic layer is coupled to the outer surface of the dielectric substrate layer.

16. (New) The mobile phone structure of claim 12 wherein the impedance layer further comprises multiple dielectric substrate layers wherein the non-ferrous metallic layer is buried between a pair of dielectric substrate layers.

17. (New) A mobile phone structure that can attenuate undesirable electro-magnetic waves prevalent at abrupt discontinuities of metallized areas within the mobile phone during normal operation of the mobile phone, the mobile phone structure comprising:

an impedance layer comprised of a resistive layer substantially covering the metallized areas wherein the resistive layer reduces the effect of undesirable electro-magnetic waves on the side of the resistive layer opposite the substantially covered metallized areas.

18. (New) The impedance layer of claim 17 further comprising a dielectric substrate layer having inner and outer surfaces coupled with the resistive layer.

19. (New) The impedance layer of claim 18 wherein the resistive layer is coupled to the inner surface of the dielectric substrate layer.

20. (New) The impedance layer of claim 18 wherein the resistive layer is coupled to the outer surface of the dielectric substrate layer.

21. (New) The impedance layer of claim 17 further comprising multiple dielectric substrate layers wherein the resistive layer is buried between a pair of dielectric substrate layers.

22. (New) A mobile phone structure that can attenuate undesirable electro-magnetic waves prevalent at abrupt discontinuities of metallized areas within the mobile phone during normal operation of the mobile phone, the mobile phone structure comprising:

an impedance layer comprised of:

a non-ferrous metallic layer; and

a resistive layer coupled with the non-ferrous metallic layer and integrated into the front cover of the mobile phone,

wherein the non-ferrous metallic layer guides undesirable electro-magnetic waves into the resistive layer where the undesirable electro-magnetic waves are attenuated thereby reducing the effect the undesirable electro-magnetic waves prevalent at abrupt discontinuities of metallized areas.